

FDQ7238AS

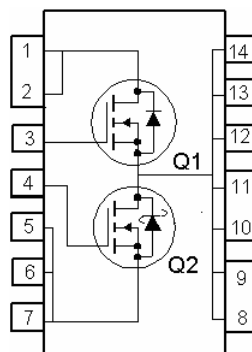
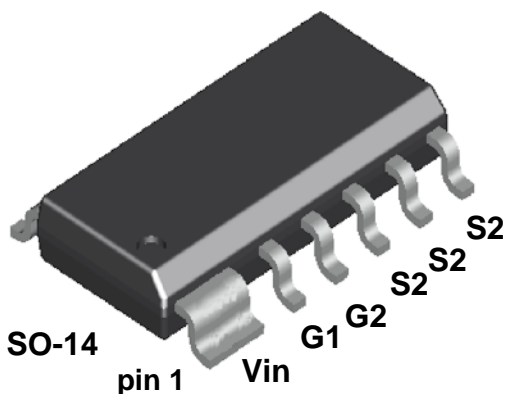
Dual Notebook Power Supply N-Channel PowerTrench® in SO-14 Package

General Description

The FDQ7238AS is designed to replace two single SO-8 MOSFETs in DC to DC power supplies. The high-side switch (Q1) is designed with specific emphasis on reducing switching losses while the low-side switch (Q2) is optimized to reduce conduction losses using Fairchild's SyncFET™ technology. The FDQ7238AS includes a patented combination of a MOSFET monolithically integrated with a Schottky diode.

Features

- **Q2:** 14 A, 30V. $R_{DS(on)} = 8.7\text{ m}\Omega @ V_{GS} = 10\text{V}$
 $R_{DS(on)} = 10.5\text{ m}\Omega @ V_{GS} = 4.5\text{V}$
- **Q1:** 11 A, 30V. $R_{DS(on)} = 13.2\text{ m}\Omega @ V_{GS} = 10\text{V}$
 $R_{DS(on)} = 16\text{ m}\Omega @ V_{GS} = 4.5\text{V}$



Absolute Maximum Ratings $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Q2	Q1	Units
V_{DSS}	Drain-Source Voltage	30	30	V
V_{GSS}	Gate-Source Voltage	± 20	± 20	V
I_D	Drain Current - Continuous (Note 1a) - Pulsed	14	11	A
		50	50	
P_D	Power Dissipation for Single Operation (Note 1a & 1b) (Note 1c & 1d)	2.4	1.8	W
		1.3	1.1	
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150		$^\circ\text{C}$

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (Note 1a & 1b) (Note 1c & 1d)	Q2	Q1	$^\circ\text{C/W}$
		52	68	
		94	118	

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
FDQ7238AS	FDQ7238AS	13"	16mm	2500 units

Electrical Characteristics

 $T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Type	Min	Typ	Max	Units
Off Characteristics							
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 1\text{ mA}$ $V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	Q2 Q1	30 30			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 10\text{ mA}$, Referenced to 25°C $I_D = 250\text{ }\mu\text{A}$, Referenced to 25°C	Q2 Q1		25 24		mV/ $^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 24\text{ V}, V_{GS} = 0\text{ V}$	Q2 Q1			500 1	μA
		$V_{DS} = 24\text{ V}, V_{GS} = 0\text{ V}, T_J = 125^\circ\text{C}$	Q2 Q1		5.6 40		mA μA
I_{GSS}	Gate-Body Leakage	$V_{GS} = \pm 20\text{ V}, V_{DS} = 0\text{ V}$	ALL			± 100	nA
On Characteristics (Note 2)							
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 1\text{ mA}$	Q2	1	1.8	3	V
		$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	Q1	1	1.7	3	
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	$I_D = 10\text{ mA}$, Referenced to 25°C $I_D = 250\text{ }\mu\text{A}$, Referenced to 25°C	Q2 Q1		-3 -4		mV/ $^\circ\text{C}$
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10\text{ V}, I_D = 14\text{ A}$	Q2		7.2	8.7	m Ω
		$V_{GS} = 4.5\text{ V}, I_D = 13\text{ A}$			8.7	10.5	
		$V_{GS} = 10\text{ V}, I_D = 14\text{ A}, T_J = 125^\circ\text{C}$			10	12.5	
		$V_{GS} = 10\text{ V}, I_D = 11\text{ A}$	Q1		11	13.2	
$I_{D(on)}$	On-State Drain Current	$V_{GS} = 10\text{ V}, V_{DS} = 5\text{ V}$	Q2	50			A
		$V_{GS} = 10\text{ V}, V_{DS} = 5\text{ V}$	Q1	50			
		$V_{GS} = 10\text{ V}, I_D = 11\text{ A}, T_J = 125^\circ\text{C}$			15	19	
g_{FS}	Forward Transconductance	$V_{DS} = 10\text{ V}, I_D = 14\text{ A}$	Q2		58		S
		$V_{DS} = 10\text{ V}, I_D = 11\text{ A}$	Q1		43		
Dynamic Characteristics							
C_{iss}	Input Capacitance	$V_{DS} = 15\text{ V}, V_{GS} = 0\text{ V}, f = 1.0\text{ MHz}$	Q2		1530		pF
			Q1		920		
C_{oss}	Output Capacitance		Q2		440		pF
			Q1		190		
C_{riss}	Reverse Transfer Capacitance	Q2		160		pF	
		Q1		120			
R_g	Gate Resistance	$V_{GS} = 15\text{ mV}, f = 1.0\text{ MHz}$	Q2		1.9		Ω
			Q1		1.9		

Electrical Characteristics

$T_A = 25^\circ\text{C}$ unless otherwise noted

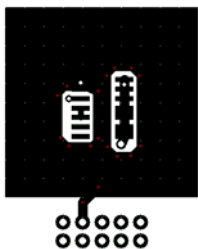
Symbol	Parameter	Test Conditions	Type	Min	Typ	Max	Units
Switching Characteristics (Note 2)							
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 15\text{ V}, I_D = 1\text{ A},$ $V_{GS} = 10\text{ V}, R_{GEN} = 6\ \Omega$	Q2		12	21	ns
			Q1		9	18	
t_r	Turn-On Rise Time		Q2		13	23	ns
			Q1		5	10	
$t_{d(off)}$	Turn-Off Delay Time		Q2		30	49	ns
			Q1		27	43	
t_f	Turn-Off Fall Time	Q2		19	35	ns	
		Q1		4	8		
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 15\text{ V}, I_D = 1\text{ A},$ $V_{GS} = 4.5\text{ V}, R_{GEN} = 6\ \Omega$	Q2		17	30	ns
			Q1		11	20	
t_r	Turn-On Rise Time		Q2		18	32	ns
			Q1		15	26	
$t_{d(off)}$	Turn-Off Delay Time		Q2		28	44	ns
			Q1		16	29	
t_f	Turn-Off Fall Time	Q2		13	23	ns	
		Q1		9	18		
$Q_{g(TOT)}$	Total Gate Charge, $V_{GS} = 10\text{ V}$	Q2 $V_{DS} = 15\text{ V}, I_D = 14\text{ A}$	Q2		28	39	nC
			Q1		17	24	
$Q_{g(TOT)}$	Total Gate Charge, $V_{GS} = 5\text{ V}$	Q1	Q2		15	21	nC
			Q1		9	19	
Q_{gs}	Gate-Source Charge	$V_{DS} = 15\text{ V}, I_D = 11\text{ A}$	Q2		4.1		nC
			Q1		2.7		
Q_{gd}	Gate-Drain Charge		Q2		4.9		nC
			Q1		3.3		

Drain-Source Diode Characteristics and Maximum Ratings

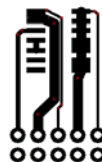
I_S	Maximum Continuous Drain-Source Diode Forward Current		Q2			3.4	A
			Q1			2.1	
V_{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = 3.4\text{ A}$ (Note 2)	Q2		0.5	0.7	V
		$V_{GS} = 0\text{ V}, I_S = 1.9\text{ A}$ (Note 2)			0.4		
		$V_{GS} = 0\text{ V}, I_S = 2.1\text{ A}$ (Note 2)	Q1		0.7	1.2	
t_{rr}	Diode Reverse Recovery Time	$I_F = 14\text{ A}$	Q2		22		ns
Q_{rr}	Diode Reverse Recovery Charge	$dI_F/dt = 300\text{ A}/\mu\text{s}$				15	nC
t_{rr}	Diode Reverse Recovery Time	$I_F = 11\text{ A}$	Q1		16		ns
Q_{rr}	Diode Reverse Recovery Charge	$dI_F/dt = 100\text{ A}/\mu\text{s}$				5	nC

NOTE :

- $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a) $68^\circ\text{C}/\text{W}$ when mounted on a 1 in^2 pad of 2 oz copper (Q1).



c) $118^\circ\text{C}/\text{W}$ when mounted on a minimum pad of 2 oz copper (Q1).

b) $52^\circ\text{C}/\text{W}$ when mounted on a 1 in^2 pad of 2 oz copper (Q2).

d) $94^\circ\text{C}/\text{W}$ when mounted on a minimum pad of 2 oz copper (Q2).

Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width < $300\mu\text{s}$, Duty Cycle < 2.0%

Typical Characteristics: Q2

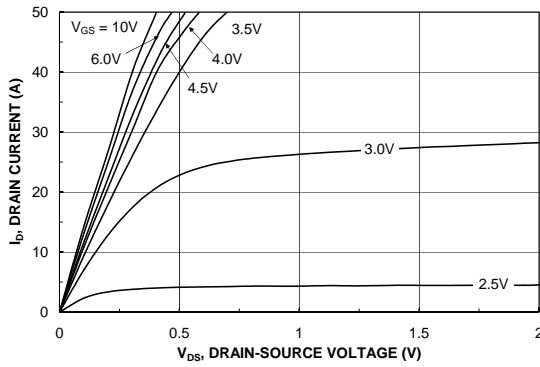


Figure 1. On-Region Characteristics.

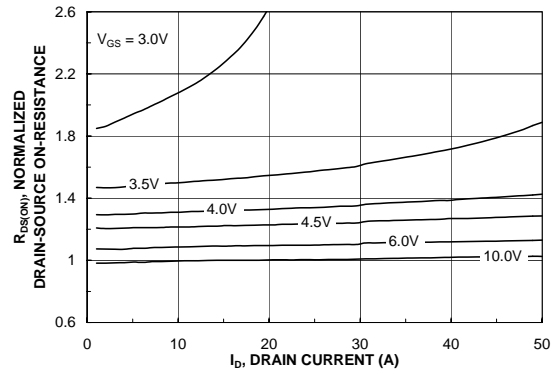


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

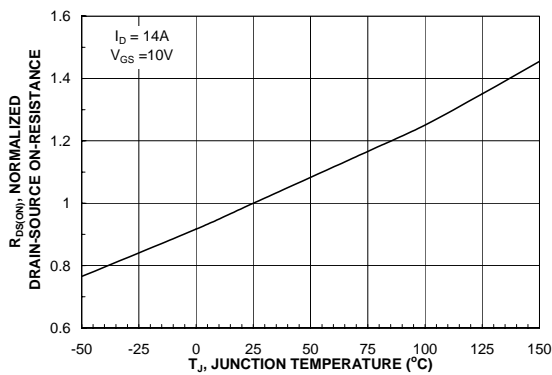


Figure 3. On-Resistance Variation with Temperature.

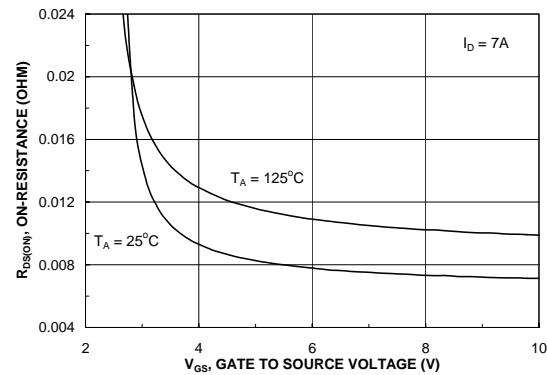


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

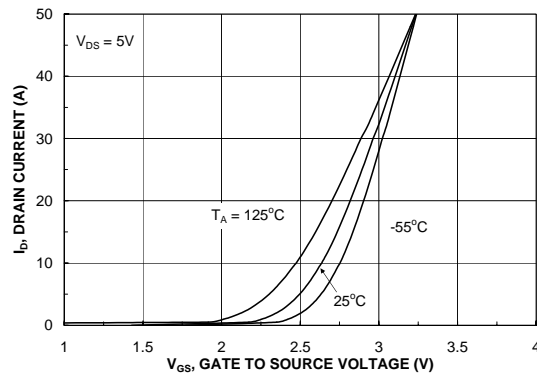


Figure 5. Transfer Characteristics.

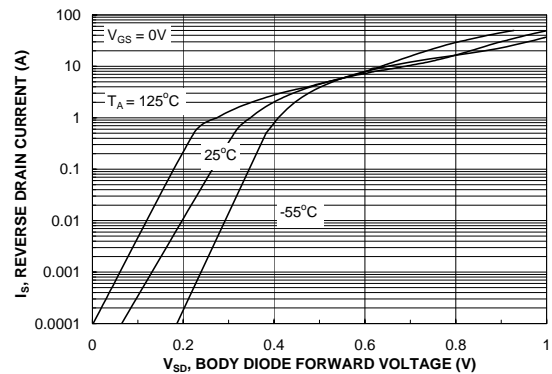


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics : Q2

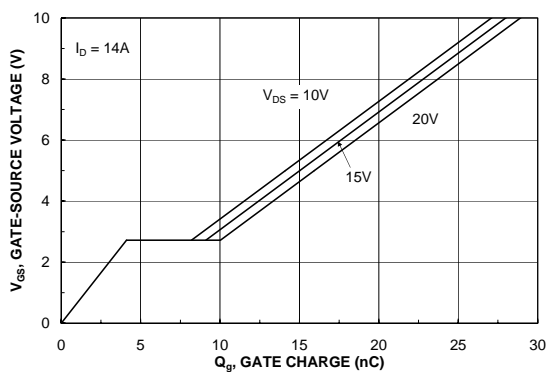


Figure 7. Gate Charge Characteristics.

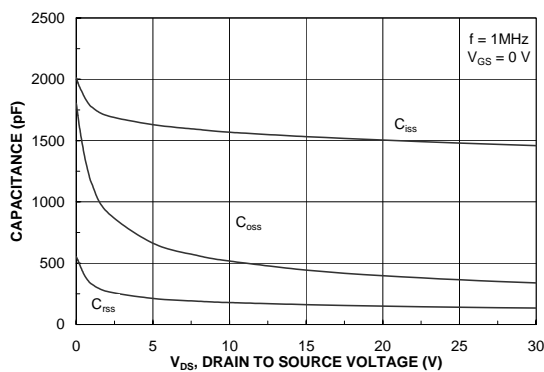


Figure 8. Capacitance Characteristics.

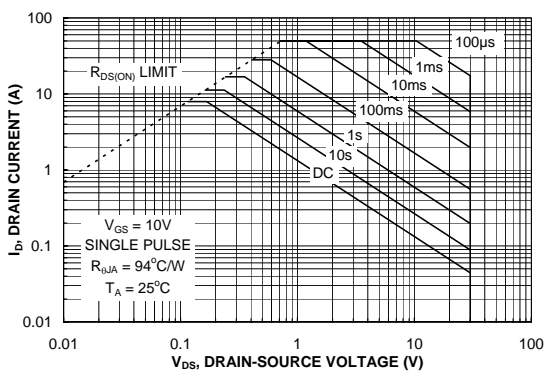


Figure 9. Maximum Safe Operating Area.

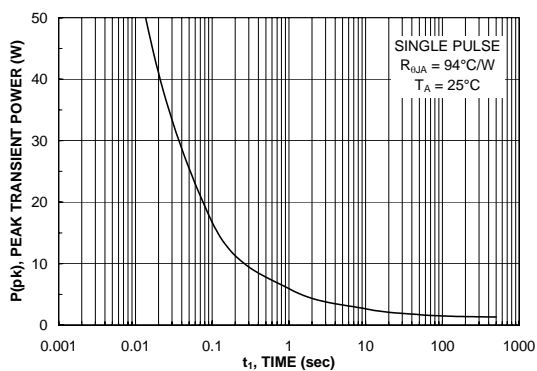


Figure 10. Single Pulse Maximum Power Dissipation.

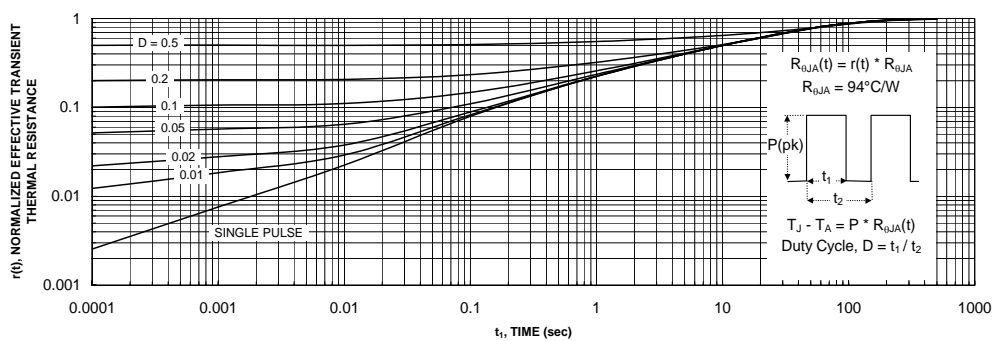


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1d.
Transient thermal response will change depending on the circuit board design

Typical Characteristics : Q2

SyncFET Schottky Body Diode Characteristics

Fairchild's SyncFET process embeds a Schottky diode in parallel with PowerTrench MOSFET. This diode exhibits similar characteristics to a discrete external Schottky diode in parallel with a MOSFET. Figure 12 shows the reverse recovery characteristic of the FDQ7238AS Q2.

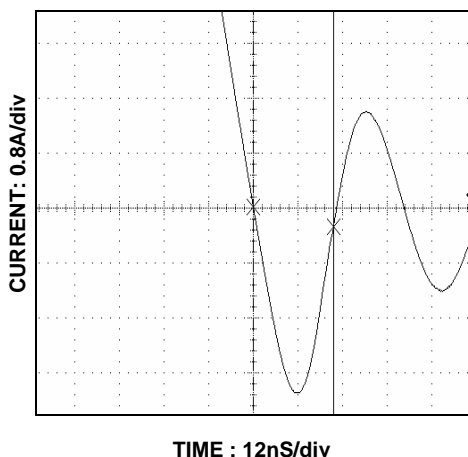


Figure 12. FDQ7238AS SyncFET body diode reverse recovery characteristic.

For comparison purposes, Figure 13 shows the reverse recovery characteristics of the body diode of an equivalent size MOSFET produced without SyncFET (FDS6670A).

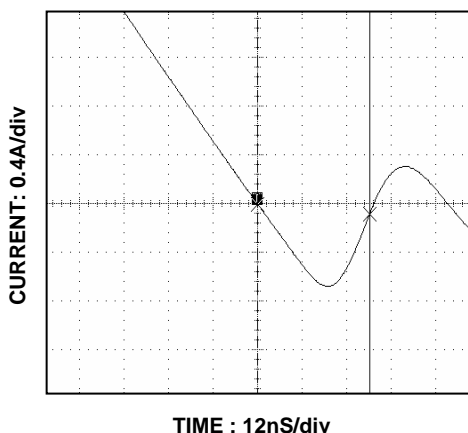


Figure 13. Non-SyncFET (FDS6670A) body diode reverse recovery characteristic.

Schottky barrier diodes exhibit significant leakage at high temperature and high reverse voltage. This will increase the power dissipated in the device.

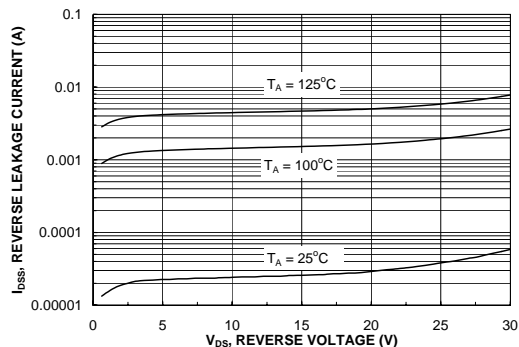


Figure 14. SyncFET body diode reverse leakage versus drain-source voltage and temperature.

Typical Characteristics: Q1

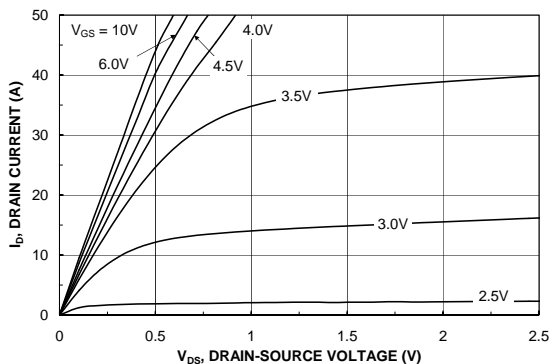


Figure 15. On-Region Characteristics.

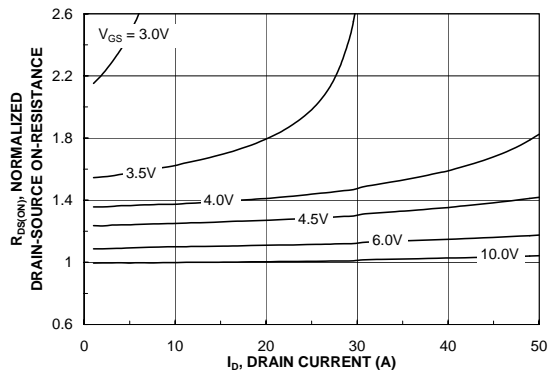


Figure 16. On-Resistance Variation with Drain Current and Gate Voltage.

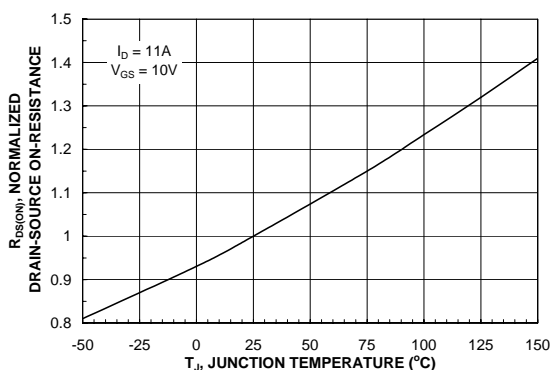


Figure 17. On-Resistance Variation with Temperature.

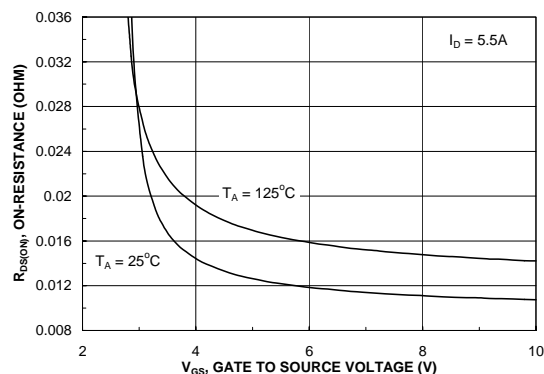


Figure 18. On-Resistance Variation with Gate-to-Source Voltage.

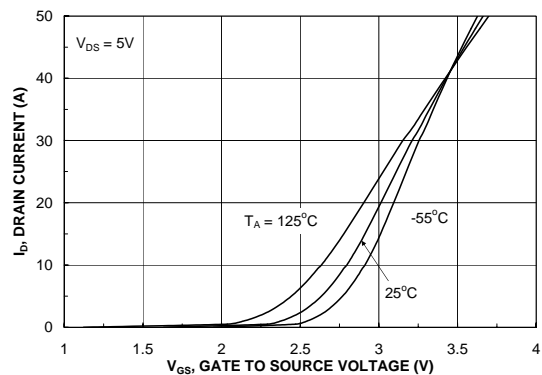


Figure 19. Transfer Characteristics.

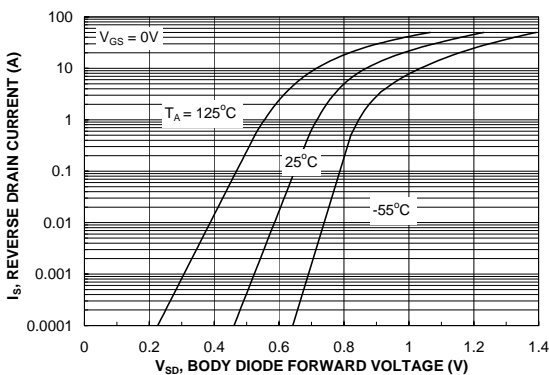


Figure 20. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics: Q1

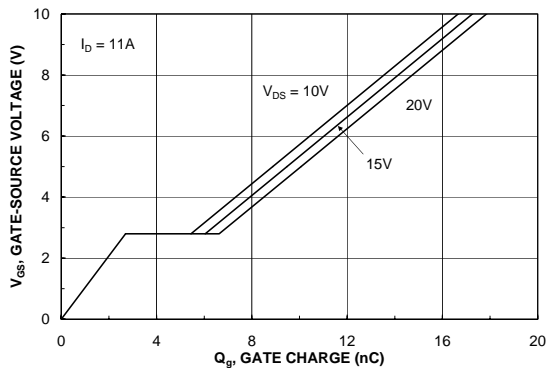


Figure 21. Gate Charge Characteristics.

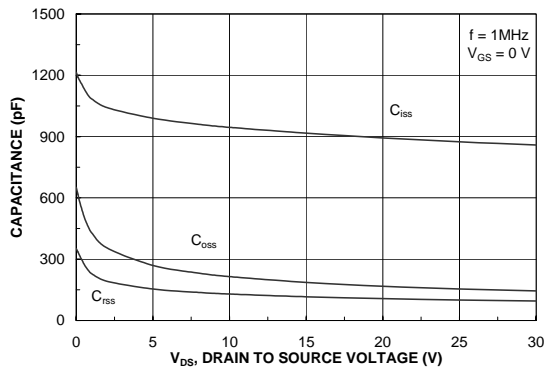


Figure 22. Capacitance Characteristics.

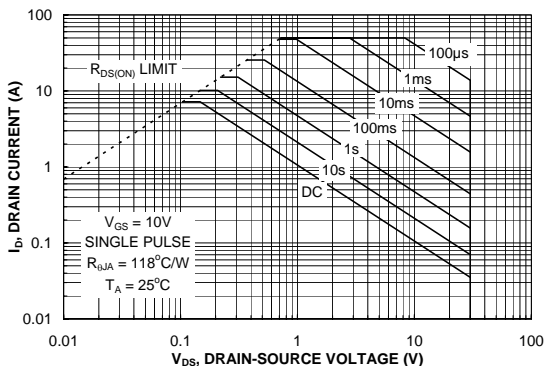


Figure 23. Maximum Safe Operating Area.

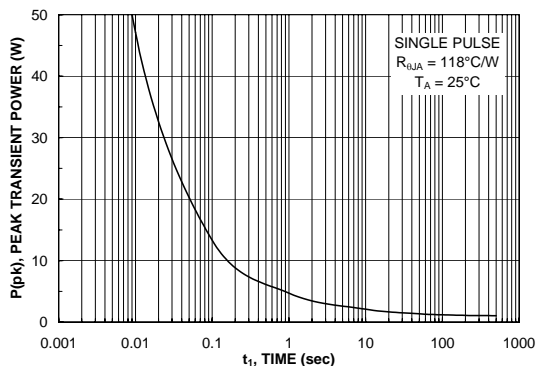


Figure 24. Single Pulse Maximum Power Dissipation.

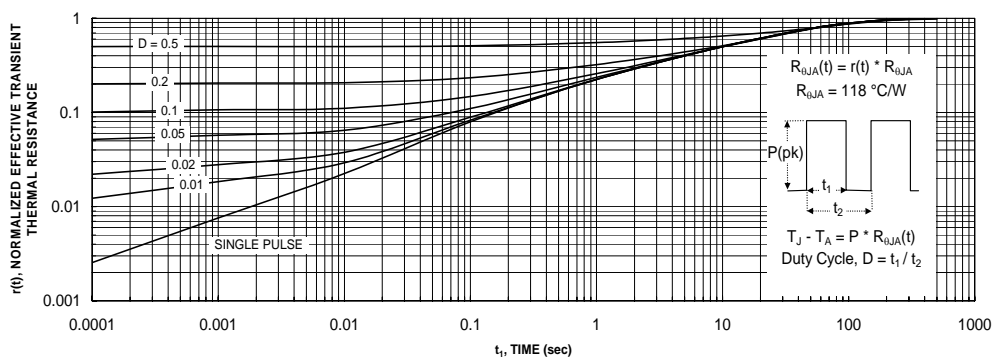







Figure 25. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c
Transient thermal response will change depending on the circuit board design.



TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

- | | | | |
|---|---|---|---|
| ACE ^x ® | FPS™ | PDP-SPM™ | The Power Franchise® |
| Build it Now™ | F-PFS™ | Power-SPM™ | power
the
franchise |
| CorePLUS™ | FRFET® | PowerTrench® | TinyBoost™ |
| CorePOWER™ | Global Power Resource SM | Programmable Active Droop™ | TinyBuck™ |
| CROSSVOLT™ | Green FPS™ | QFET® | TinyLogic® |
| CTL™ | Green FPS™ e-Series™ | QS™ | TINYOPTO™ |
| Current Transfer Logic™ | GTO™ | Quiet Series™ | TinyPower™ |
| EcoSPARK® | IntelliMAX™ | RapidConfigure™ | TinyPWM™ |
| EfficientMax™ | ISOPLANAR™ | Saving our world 1mW at a time™ | TinyWire™ |
| EZSWITCH™ * | MegaBuck™ | SmartMax™ | µSerDes™ |
|  | MICROCOUPLER™ | SMART START™ |  |
|  | MicroFET™ | SPM® | UHC® |
| Fairchild® | MicroPak™ | STEALTH™ | Ultra FRFET™ |
| Fairchild Semiconductor® | MillerDrive™ | SuperFET™ | UniFET™ |
| FACT Quiet Series™ | MotionMax™ | SuperSOT™-3 | VCX™ |
| FACT® | Motion-SPM™ | SuperSOT™-6 | VisualMax™ |
| FAST® | OPTOLOGIC® | SuperSOT™-8 | |
| FastvCore™ | OPTOPLANAR® | SuperMOS™ | |
| FlashWriter® * |  |  | |

* EZSWITCH™ and FlashWriter® are trademarks of System General Corporation, used under license by Fairchild Semiconductor.

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	This datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
Obsolete	Not In Production	This datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.